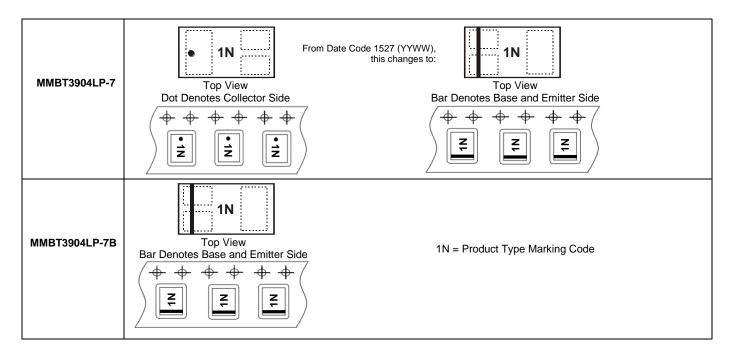


# **Marking Information**



# Absolute Maximum Ratings (@T<sub>A</sub> = +25°C, unless otherwise specified.)

Characteristic	Symbol	Value	Unit
Collector-Base Voltage	V <sub>CBO</sub>	60	V
Collector-Emitter Voltage	V <sub>CEO</sub>	40	V
Emitter-Base Voltage	V <sub>EBO</sub>	6.0	V
Collector Current	lc	200	mA
Peak Collector Current	ICM	200	mA

### Thermal Characteristics (@T<sub>A</sub> = +25°C, unless otherwise specified.)

Characteristic		Symbol	Value	Unit	
Power Dissipation	(Note 5)	Р	400	mW	
	(Note 6)	- P <sub>D</sub>	1000		
Thermal Desistance, lunction to Archient	(Note 5)	R <sub>0JA</sub>	310	°C/W	
Thermal Resistance, Junction to Ambient	(Note 6)		120		
Thermal Resistance, Junction to Lead	(Note 7)	R <sub>θJL</sub>	120	°C/W	
Operating and Storage and Temperature Ran	ge	T <sub>J</sub> , T <sub>STG</sub>	-55 to +150	°C	

# ESD Ratings (Note 8)

Characteristic	Symbol	Value	Unit	JEDEC Class
Electrostatic Discharge - Human Body Model	ESD HBM	4,000	V	3A
Electrostatic Discharge - Machine Model	ESD MM	200	V	В

Notes: 5. For the device mounted on minimum recommended pad layout 1oz copper that is on a single-sided 1.6mm FR4 PCB; device is measured under still air conditions whilst operating in steady state condition. The entire exposed collector pad is attached to the heatsink.

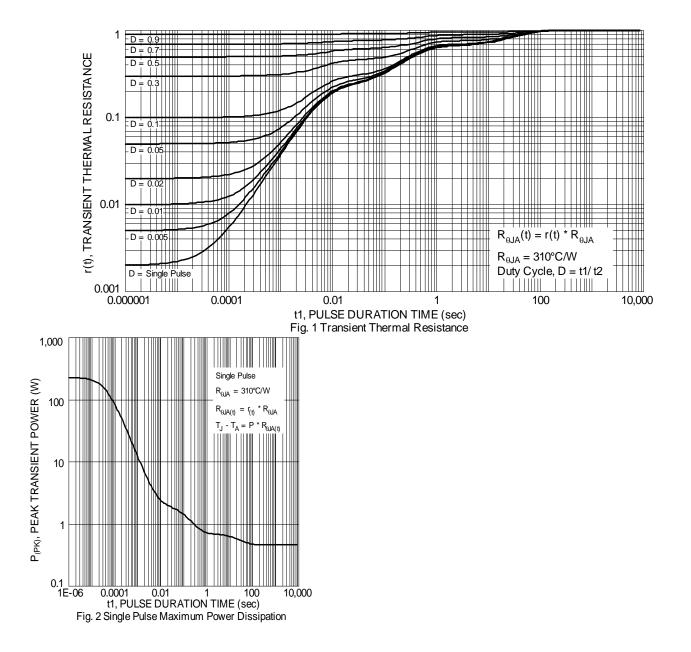
6. Same as Note 5, except the exposed collector pad is mounted on 25mm x 25mm 2oz copper.

7. Thermal resistance from junction to solder-point (on the exposed collector pad).

8. Refer to JEDEC specification JESD22-A114 and JESD22-A115.



# **Thermal Characteristics**





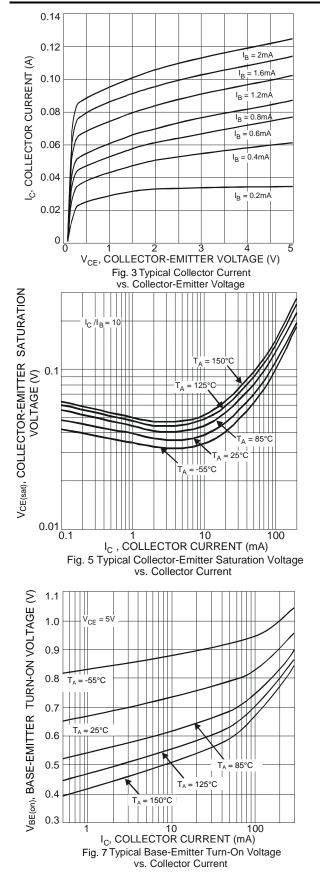
# Electrical Characteristics (@T<sub>A</sub> = +25°C, unless otherwise specified.)

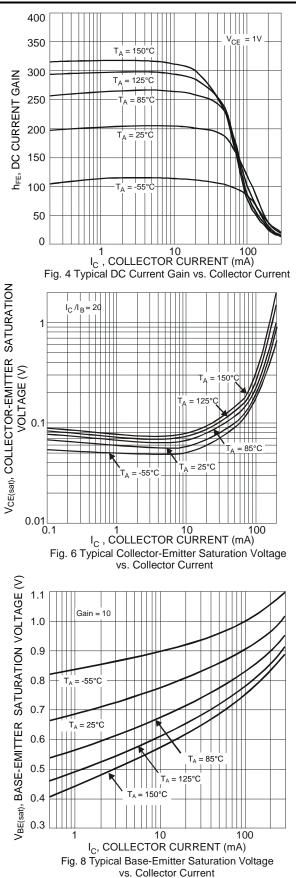
Characteristic	Symbol	Min	Max	Unit	Test Condition
OFF CHARACTERISTICS					
Collector-Base Breakdown Voltage	BV <sub>CBO</sub>	60		V	$I_{\rm C} = 10 \mu A, I_{\rm E} = 0 A$
Collector-Emitter Breakdown Voltage (Note 9)	BV <sub>CEO</sub>	40	_	V	$I_{\rm C} = 1.0 {\rm mA}, I_{\rm B} = 0{\rm A}$
Emitter-Base Breakdown Voltage	BV <sub>EBO</sub>	6.0	_	V	$I_{E} = 10\mu A, I_{C} = 0A$
Collector Cutoff Current	ICEX	_	50	nA	$V_{CE} = 30V, V_{EB(off)} = 3.0V$
Base Cutoff Current	I <sub>BL</sub>	_	50	nA	$V_{CE} = 30V, V_{EB(off)} = 3.0V$
ON CHARACTERISTICS (Note 9)					
		40			$I_{C} = 100 \mu A, V_{CE} = 1.0 V$
		70	_		$I_{C} = 1.0 \text{mA}, V_{CE} = 1.0 \text{V}$
DC Current Gain	h <sub>FE</sub>	100	300	_	$I_{C} = 10 \text{mA}, V_{CE} = 1.0 \text{V}$
		60	_		$I_{C} = 50 \text{mA}, V_{CE} = 1.0 \text{V}$
	30 —	_		I <sub>C</sub> = 100mA, V <sub>CE</sub> = 1.0V	
Collector-Emitter Saturation Voltage			0.20	V	I <sub>C</sub> = 10mA, I <sub>B</sub> = 1.0mA
	V <sub>CE(sat)</sub>	_	0.30		I <sub>C</sub> = 50mA, I <sub>B</sub> = 5.0mA
Base-Emitter Saturation Voltage		0.65	0.85	V	I <sub>C</sub> = 10mA, I <sub>B</sub> = 1.0mA
Dase-Elline Saturation Voltage	V <sub>BE(sat)</sub>	_	0.95	v	$I_{\rm C} = 50 {\rm mA}, I_{\rm B} = 5.0 {\rm mA}$
SMALL SIGNAL CHARACTERISTICS					
Output Capacitance	Cobo	_	4.0	pF	$V_{CB} = 5.0V$ , f = 1.0MHz, I <sub>E</sub> = 0A
Input Capacitance	C <sub>ibo</sub>		8.5	pF	$V_{EB} = 0.5V$ , f = 1.0MHz, I <sub>C</sub> = 0A
Input Impedance	h <sub>ie</sub>	1.0	10	kΩ	
Voltage Feedback Ratio	h <sub>re</sub>	0.5	8.0	x 10 <sup>-4</sup>	$V_{CE} = 10V, I_{C} = 1.0mA,$
Small Signal Current Gain	h <sub>fe</sub>	100	400		f = 1.0 kHz
Output Admittance	h <sub>oe</sub>	1.0	40	μs	
Current Gain-Bandwidth Product	f <sub>T</sub>	300	—	MHz	$V_{CE} = 20V, I_{C} = 10mA,$ f = 100MHz
SWITCHING CHARACTERISTICS	•		•	•	·
Delay Time	t <sub>d</sub>	_	35	ns	$V_{CC} = 3.0V, I_{C} = 10mA,$
Rise Time	tr		35	ns	$V_{BE(off)} = 0.5V, I_{B1} = 1.0mA$
Storage Time	ts	_	200	ns	$V_{CC} = 3.0V, I_C = 10mA,$
Fall Time	t <sub>f</sub>	_	50	ns	$I_{B1} = -I_{B2} = 1.0 \text{mA}$

Note: 9. Measured under pulsed conditions. Pulse width  $\leq$  300µs. Duty cycle  $\leq$  2%.



### Typical Electrical Characteristics (@T<sub>A</sub> = +25°C, unless otherwise specified.)

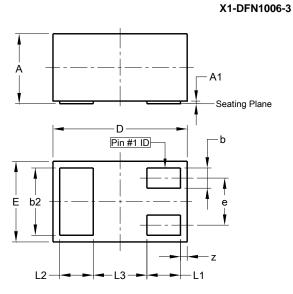






# **Package Outline Dimensions**

Please see http://www.diodes.com/package-outlines.html for the latest version.



Х	X1-DFN1006-3				
Dim	Min	Max	Тур		
Α	0.47	0.53	0.50		
A1	0.00	0.05	0.03		
b	0.10	0.20	0.15		
b2	0.45	0.55	0.50		
D	0.95	1.075	1.00		
Е	0.55	0.675	0.60		
е	1	-	0.35		
L1	0.20	0.30	0.25		
L2	0.20	0.30	0.25		
L3	-	-	0.40		
z	0.02	0.08	0.05		
All Di	All Dimensions in mm				

# Suggested Pad Layout

Please see http://www.diodes.com/package-outlines.html for the latest version.

Y –

Y1

G2 -



-⊢G1

- X1

Dimensions	Value (in mm)
С	0.70
G1	0.30
G2	0.20
Х	0.40
X1	1.10
Y	0.25
Y1	0.70

X1-DFN1006-3



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  - 2. support or sustain life and whose failure to perform when properly used in accordance with instructions for use provided in the labeling can be reasonably expected to result in significant injury to the user.

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